

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP Exp. Pad

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**TOTAL MASS (g) : 0.093353**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001954	1000000	20931.2226562		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.030596	975000	327743.96875		
		Iron (Fe)	7439-89-6	0.000753	24000	8066.12695312		
		Phosphorus (P)	7723-14-0	0.000009	300	96.4078903198		
		Zinc (Zn)	7440-66-6	0.000022	700	235.663742065		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.031380</b>	<b>1000000</b>	<b>336142.21875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002480	1000000	26569.5214844		
		<b>External Plating Total:</b>				<b>0.002480</b>	<b>1000000</b>	<b>26569.5214844</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000806	1000000	8633.86230469		
<b>Internal Plating Total:</b>				<b>0.000806</b>	<b>1000000</b>	<b>8633.86230469</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000687	750000	7359.13525391		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000229	250000	2453.04516602		
<b>Die Attach Total:</b>				<b>0.000916</b>	<b>1000000</b>	<b>9812.18066406</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.007460	135000	79911.4296875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.047524	860000	509076.53125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000276	5000	2956.50854492		
		<b>Encapsulation Total:</b>				<b>0.055260</b>	<b>1000000</b>	<b>591944.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000557	1000000	5966.57714844		
					<b>TOTAL MASS (g) :</b>	<b>0.093353</b>		